Product End-of-Life Disassembly Instructions

Marketing Name / Model [List multiple models if applicable.]	Product Category - Servers
Product Name	HP Integrity Superdome 2 CB900s i2/i4 IOX Enclosure
Model:	CB900s i2/i4

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	Each IOX assembly contains the following PCAs: AH338-60401 IO Backplane AH338-60104 OLRL AH338-60103 OLRR AH338-60002 BIODCB The IOX assembly is configurable with PCIe cards and may contain some of the following assemblies. Maximum total PCIe cards is 12: AD221A - 1p 4Gb FC/1p 1000BT adaptor AD222A - 2p 4Gb FC/2p 1000BT adaptor AD393A – 2p 4Gb FC/2p 1000BSX adaptor AD338A – 2-port 1000Base-SX card AD337A – 2-port 1000Base-T card AD339A – 4-port 1000Base-T Gigabit adaptor AH400A – 1-port 8Gb FC SR Qlogic HBA AH401A – 2-port 8Gb FC SR Qlogic HBA	17 (maximum)
Batteries		
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB / PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Per Power Supply	1
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screw drivers	T10, T15 & T25
Flat Blade Screwdriver	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. If IOX is racked remove from rack
    - Caution: IOX should be removed using two people it is ~65lbs
    - Extend the IOX enclosure from the rack

- If any cables installed onto the IOX assembly unplug
- Depress tabs on rails to and pull IOX out of the rack
- Place on flat surface to continue disassembly

2. Remove IOX access panel (See Figure 1)
    - Unlock the cam on the access panel latch by turning the lock on the latch counterclockwise with a T15 Torx screwdriver
    - Pull up on the access panel latch
        - This causes the access panel to slide back by about 1.75cm
    - Remove the access panel by lifting it straight up and off the IOX enclosure
3. If installed remove the PCI-e cards
    - Open the slot release lever on populated slots by pressing the release latch and flipping the lever up
    - Firmly pull the PCIe card divider up
    - Remove the PCIe card from the slot
4. Remove the power supplies (quantity 2)
    - Disconnect the ac power cord from the power supply
    - Press on the release latch
    - Pull the power supply out while holding the release latch (See Figure 2)
5. Remove the IOX fans (quantity 4)
    - Press the release tabs together
    - Pull the fan up by gripping the release tabs (See Figure 3)
6. Remove the IOX PSU tunnel (See Figure 4)
    - Press the release latches at the front end of the tunnel
    - Lift and tilt the tunnel upward while gripping the release latches
    - Pull the tunnel up and out of the enclosure
7. Remove the IOX I/O backplane (See Figure 5)
    - Disconnect the OL* board connectors
    - Lift the I/O backplane release lever
    - Lift the I/O backplane up and out of the enclosure

8. Remove the IOX OL* boards (quantity 2) (See Figure 6)
    - Remove the screws on each side of the board
    - Lift the board up and out of the enclosure
9. Disassemble the I/O backplane assembly
    - Remove the 8 screws holding the PCI separator blocks(quantity 4 separator blocks) (See Figure 7)
    - May have to bend the dividers to reach the screws
    - After screws are removed should be able to lift the PCIe dividers and separator blocks out
    - Remove the DC transfer boards (quantity 2) (See Figure 8)
    - Remove the DC transfer board support (quantity 1) (See Figure 9)
    - Unplug OL* cables from PCA (See Figure 10)
    - Remove card cage Right, card cage Left and Fan cage (See Figure 11)
    - Lift the PCA off of the support frame
10. Remove Power Supply covers
    - Locate CAP greater than 2.5cm (See Figure 12)
    - Using a flat blade screwdriver remove Capacitors, 1 per supply
    - Note: There are two different vendor power supplies Figure 12 will show location of capacitor for both vendors

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

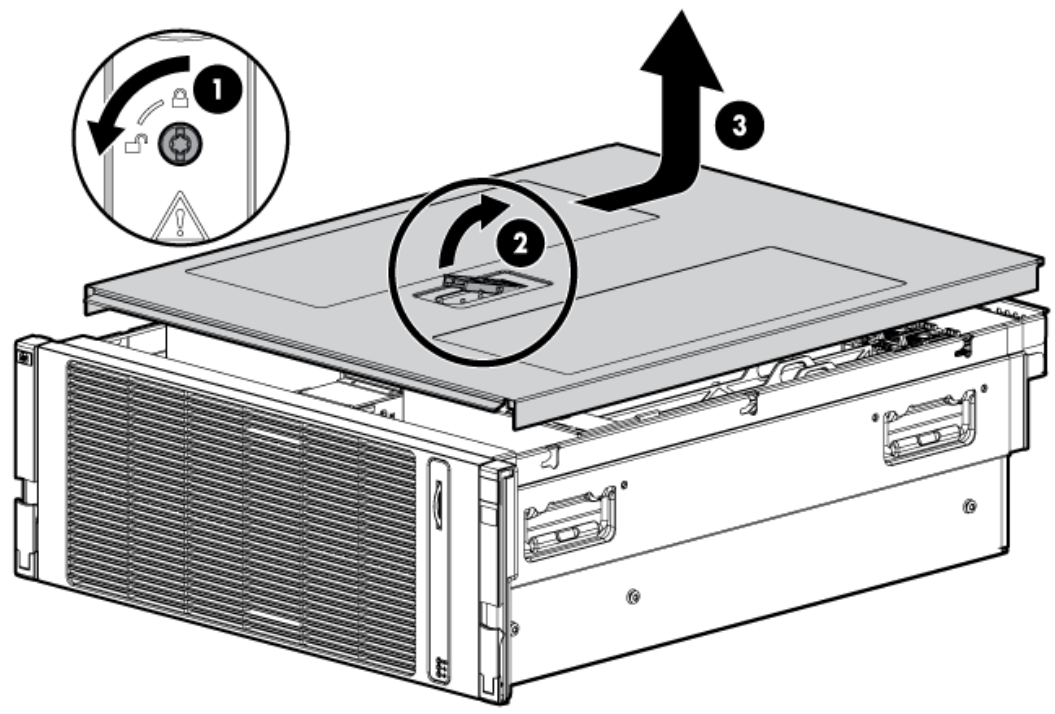


FIGURE 1

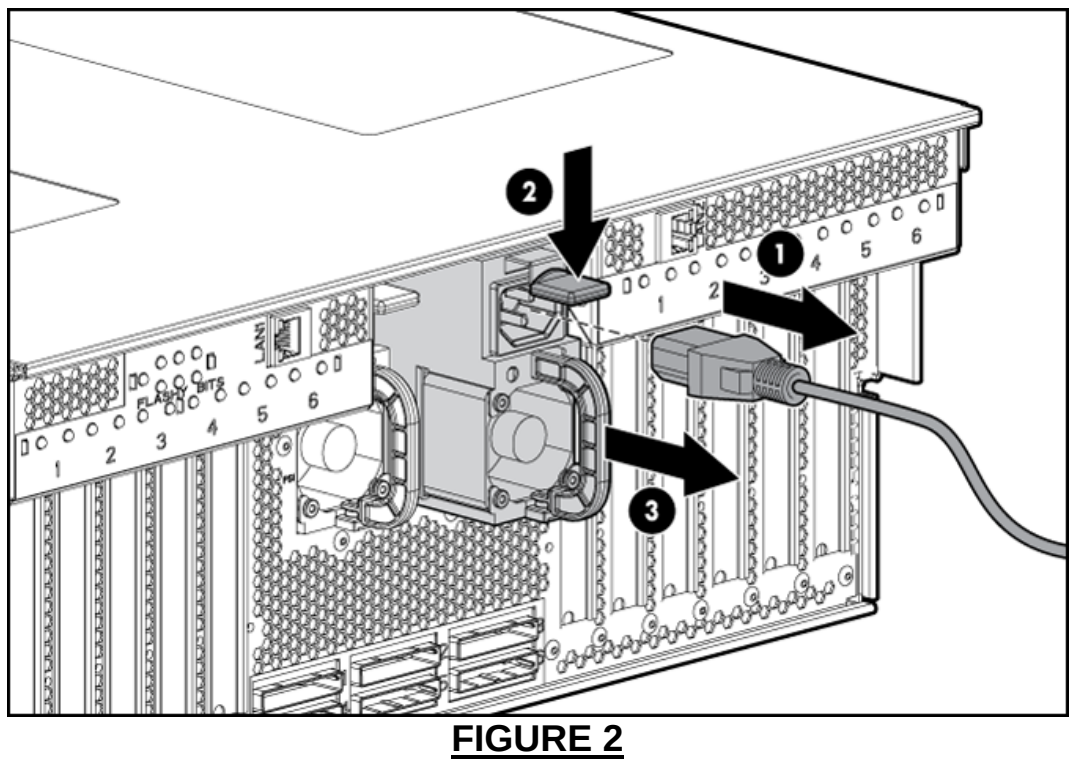


FIGURE 2

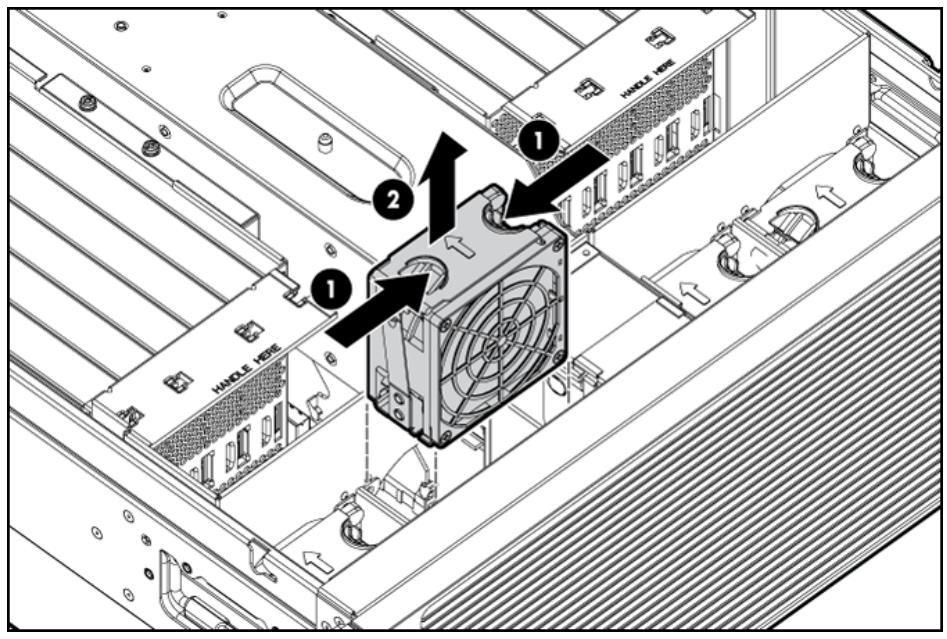


FIGURE 3

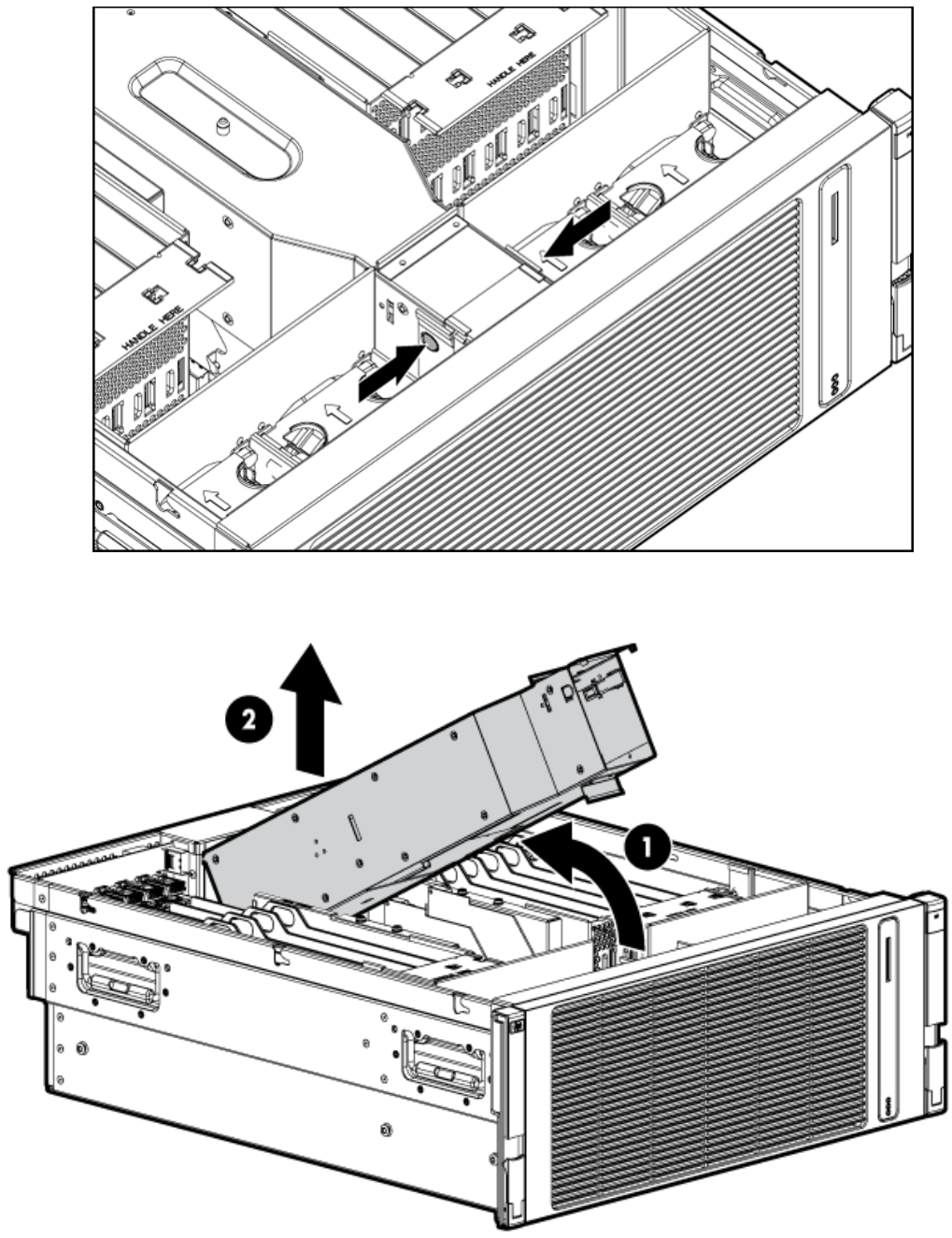
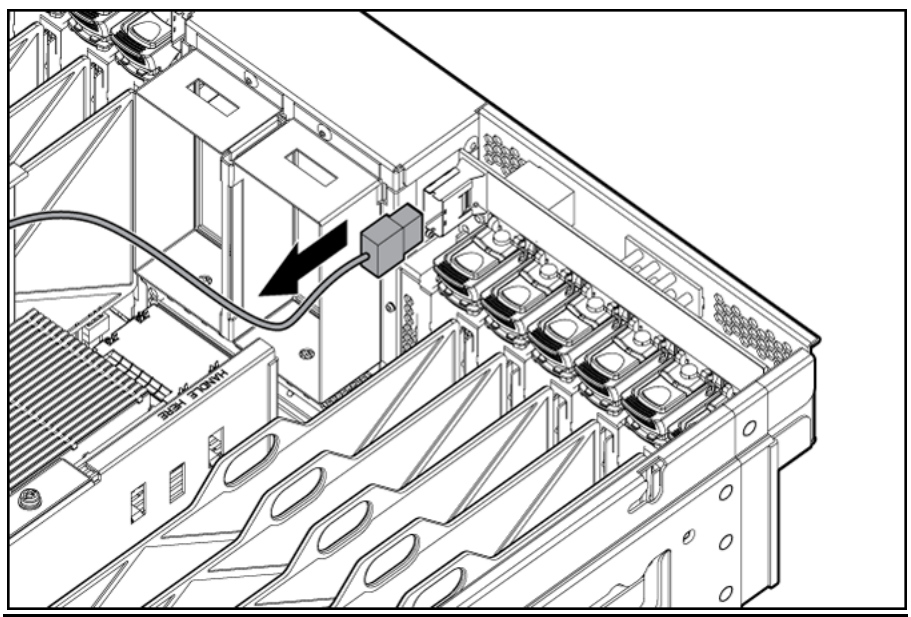
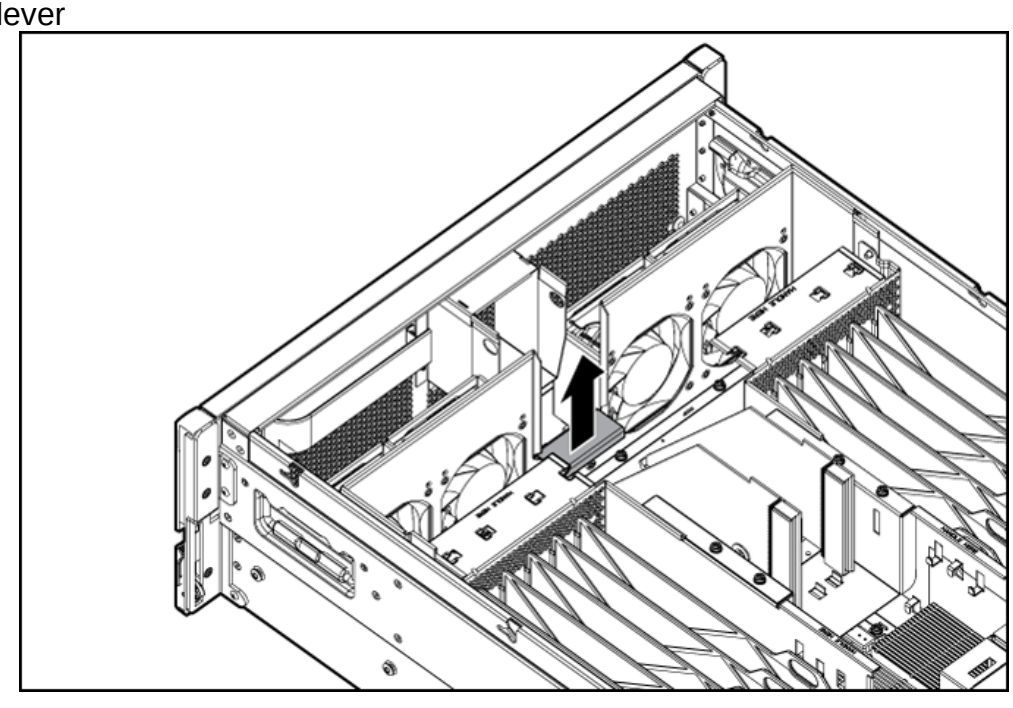


FIGURE 4

- Disconnect the OL* board connectors



- Lift the I/O backplane release lever



- Lift the I/O backplane up and out of the enclosure

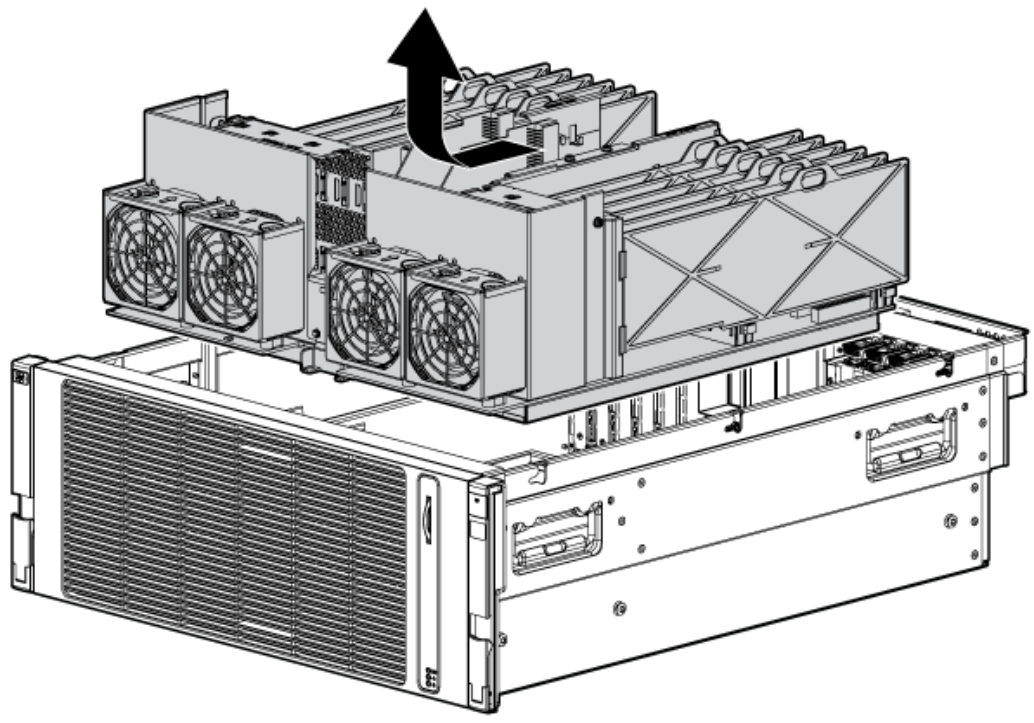


FIGURE 5

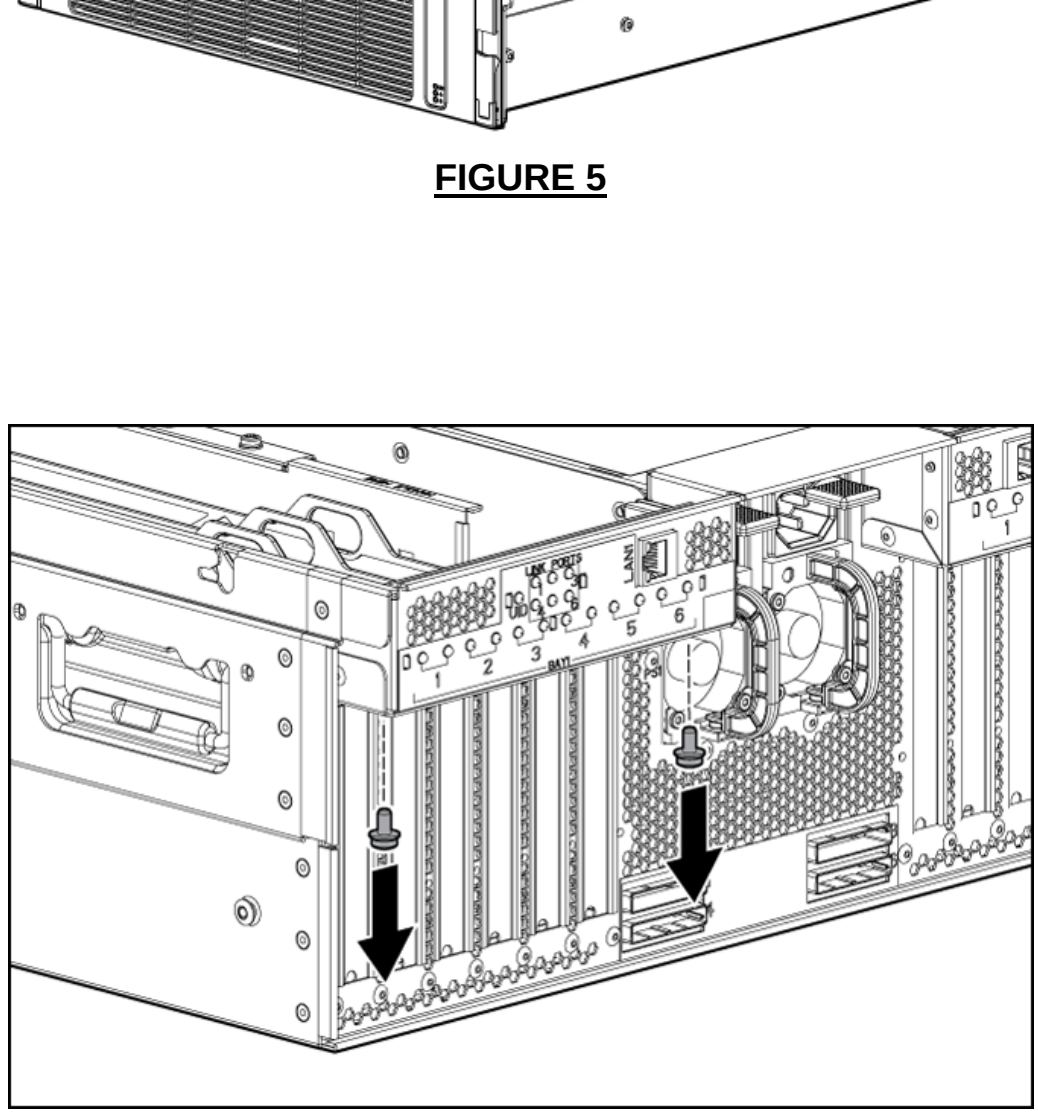


FIGURE 6

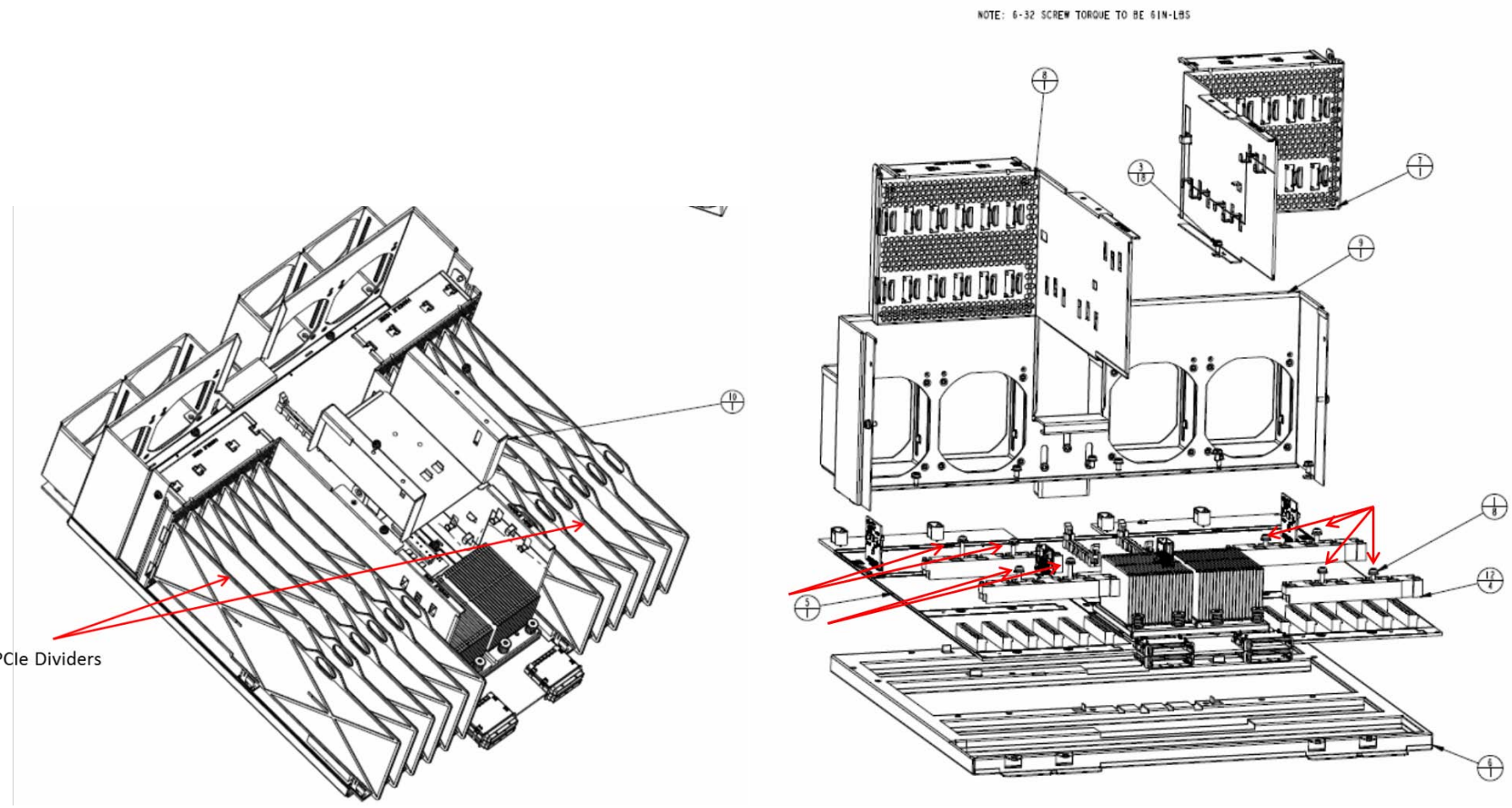


FIGURE 7

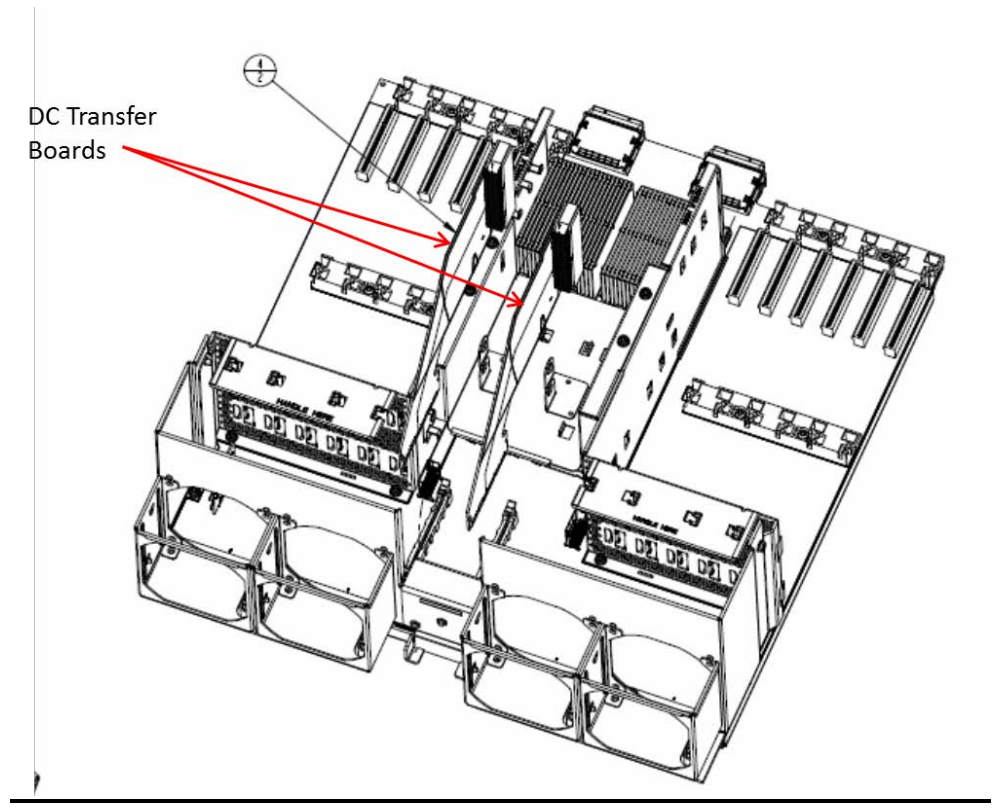


FIGURE 8

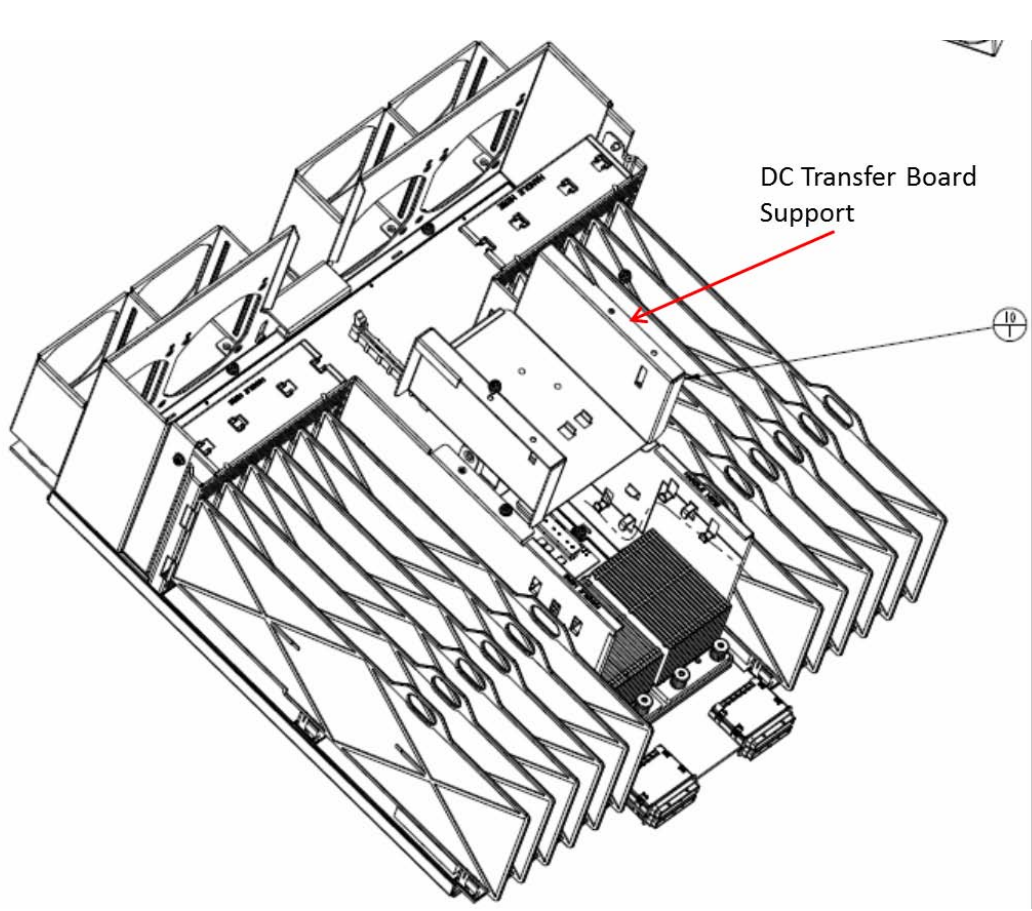


FIGURE 9

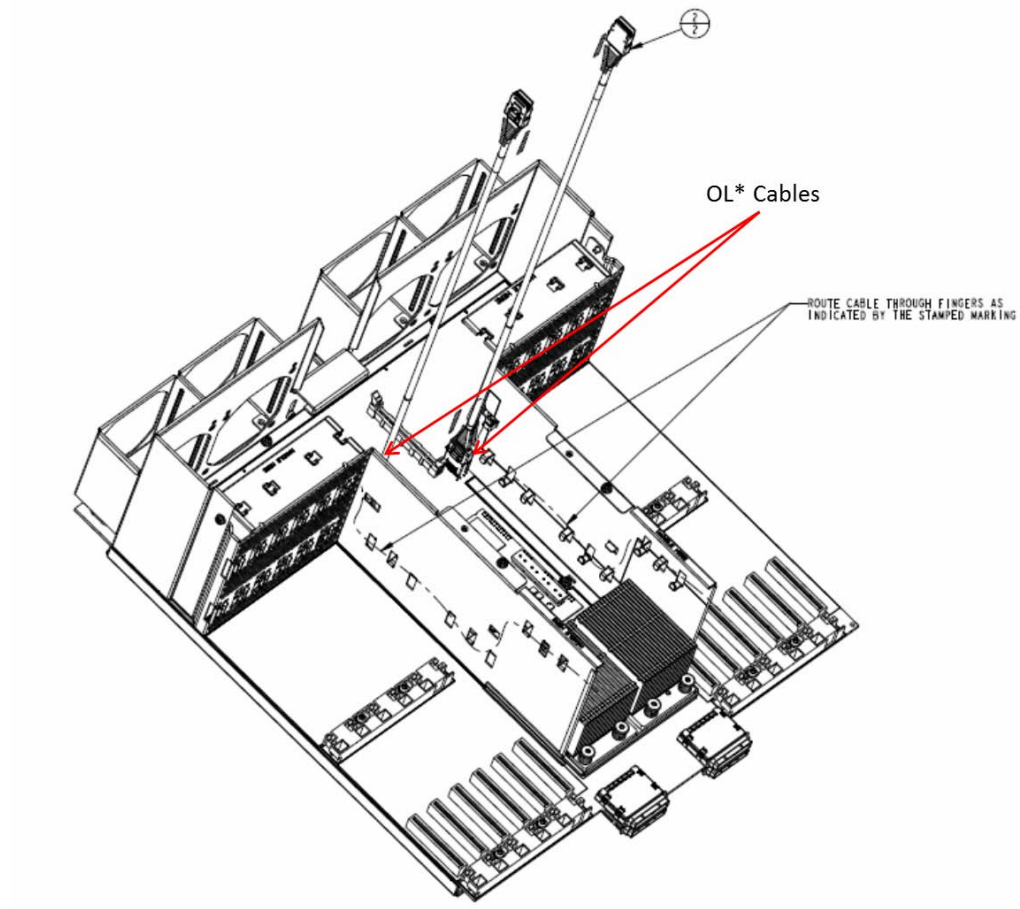


FIGURE 10

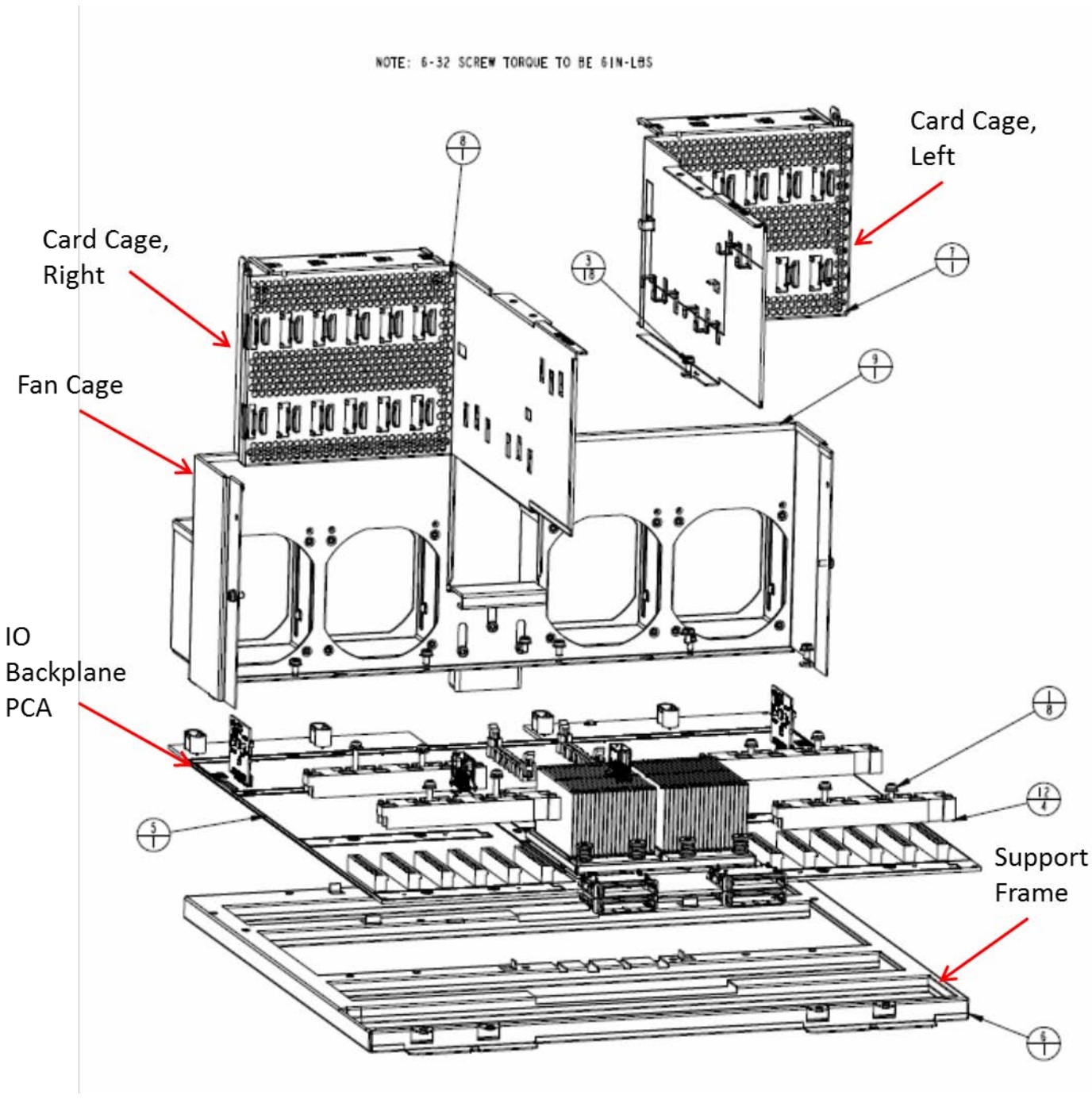


FIGURE 11

Above is for the P/N: 506822-101 Power Supply; Below is for P/N: 506822-201 power supplies

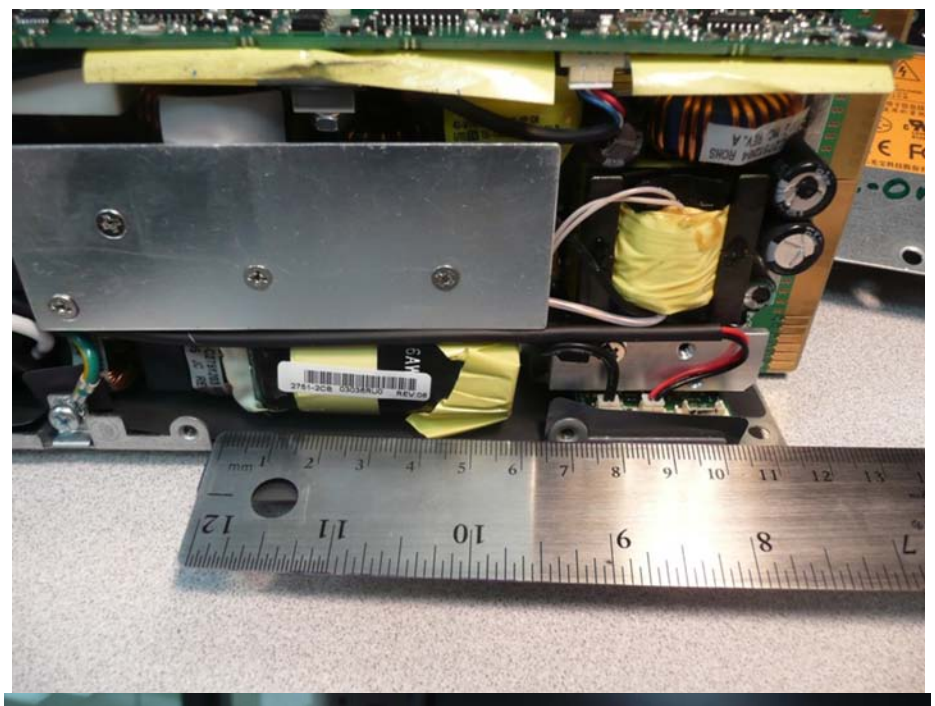


FIGURE 12